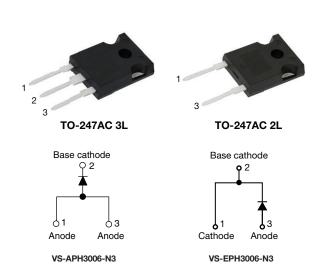


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Hyperfast Rectifier, 30 A FRED Pt®



PRIMARY CHARACTERISTICS						
I _{F(AV)}	30 A					
V_{R}	600 V					
V _F at I _F	1.4 V					
t _{rr} typ.	27 ns					
T _J max.	175 °C					
Package	TO-247AC 3L, TO-247AC 2L					
Circuit configuration	Single					

FEATURES

- · Low forward voltage drop
- Hyperfast soft recovery time
- 175 °C operating junction temperature
- Designed and qualified according to JEDEC®-JESD 47





DESCRIPTION / APPLICATIONS

Hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time, and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC Boost stage in the AC/DC section of SMPS, inverters or as freewheeling diodes.

The extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS							
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS			
Repetitive peak reverse voltage	V_{RRM}		600	V			
Average rectified forward current	I _{F(AV)}	T _C = 112 °C	30	۸			
Non-repetitive peak surge current	I _{FSM}	$T_C = 25 {}^{\circ}\text{C}, t_p = 10 \text{ms}$	220	A			
Operating junction and storage temperatures	T _J , T _{Stg}		-65 to +175	°C			

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Breakdown voltage, blocking voltage	V _{BR} , V _R	Ι _R = 100 μΑ	600	-	-		
Farmend malkage	V _F	I _F = 30 A	-	2.0	2.65 V		
Forward voltage		I _F = 30 A, T _J = 150 °C	-	1.4	1.8		
Dayaraa laakaaa ayyyant	I _R	$V_R = V_R$ rated	-	-	30		
Reverse leakage current		$T_J = 150 ^{\circ}\text{C}, V_R = V_R \text{rated}$		-	300	μΑ	
Junction capacitance	C _T	V _R = 600 V	-	20	-	pF	
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8.0	-	nH	

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DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST (CONDITIONS	MIN.	TYP.	MAX.	UNITS		
		$I_F = 1 A, dI_F/dt = 50$	0 A/μs, V _R = 30 V	-	26	35			
Reverse recovery time	t _{rr}	T _J = 25 °C	$I_F = 30 \text{ A}$ $dI_F/dt = 200 \text{ A/}\mu\text{s}$ $V_R = 200 \text{ V}$	-	26	-	ns - A		
		T _J = 125 °C		-	70	-			
Peak recovery current	I _{RRM}	T _J = 25 °C		-	3.5	-			
		T _J = 125 °C		-	7.6	-			
Davis and a second and a second	0	T _J = 25 °C		-	50	-	~C		
Reverse recovery charge	Q_{rr}	T _J = 125 °C		-	280	-	nC		

THERMAL - MECHANICAL SPECIFICATIONS								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS		
Maximum junction and storage temperature range	T _J , T _{Stg}		-65	-	175	°C		
Thermal resistance, junction to case	R_{thJC}		ı	0.7	1.1	°C/W		
Thermal resistance, junction to ambient per leg	R_{thJA}	Typical socket mount	-	-	40			
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth, and greased	-	0.5	-			
Weight			-	5.5	=	g		
vveigni			-	0.2	-	OZ.		
Mounting torque			1.2 (10)	-	2.4 (20)	kgf · cm (lbf · in)		
Made at a de tar		Case style TO-247AC 3L	APH3006					
Marking device		Case style TO-247AC 2L		EPH3006				

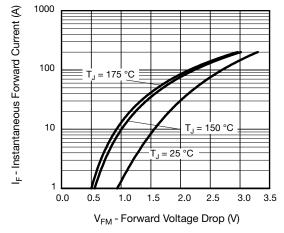


Fig. 1 - Typical Forward Voltage Drop Characteristics

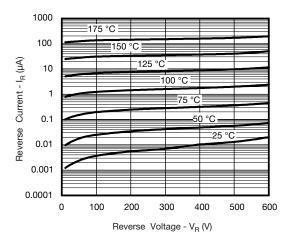


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

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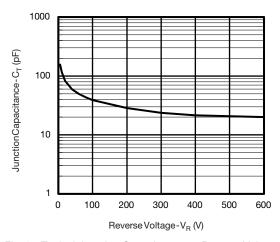


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

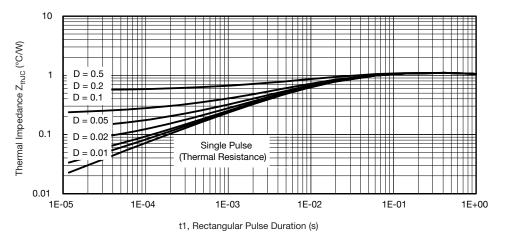


Fig. 4 - Max. Thermal Impedance Z_{thJC} Characteristics

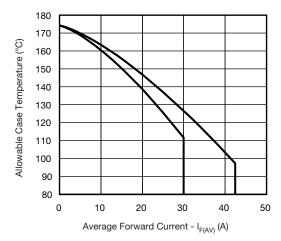


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

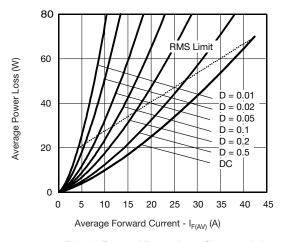
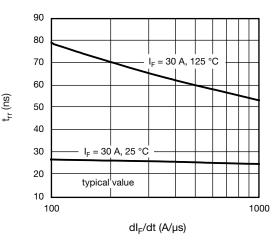


Fig. 6 - Forward Power Loss Characteristics



VS-APH3006-N3, VS-EPH3006-N3

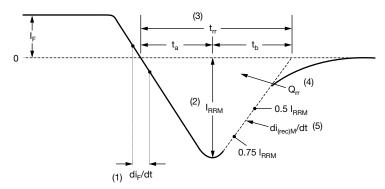
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900 800 700 600 I_E = 30 A, 125 °C Q_{rr} (nC) 500 400 300 200 I_F = 30 A, 25 °C 10 typical value 0 100 1000 dI_F/dt (A/ μ s)

Fig. 7 - Typical Reverse Recovery vs. dl_F/dt

Fig. 8 - Typical Stored Charge vs. dl_F/dt



- (1) di_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) $t_{\rm rr}$ reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RRM} and 0.50 I_{RRM} extrapolated to zero current.
- (4) Q_{rr} area under curve defined by t_{rr} and I_{RRM}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 9 - Reverse Recovery Waveform and Definitions

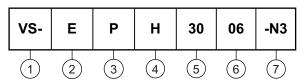


VS-APH3006-N3, VS-EPH3006-N3

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ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - Circuit configuration

• E = single diode, 2 pins

• A = single diode, 3 pins

3 - P = TO-247AC

4 - H = hyperfast recovery time

5 - Current code (30 = 30 A)

6 - Voltage code (06 = 600 V)

7 - Environmental digit:

-N3 = halogen-free, RoHS-compliant and totally lead (Pb)-free

ORDERING INFORMATION (Example)						
PREFERRED P/N	QUANTITY PER TUBE	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION			
VS-APH3006-N3	25	500	Antistatic plastic tube			
VS-EPH3006-N3	25	500	Antistatic plastic tube			

LINKS TO RELATED DOCUMENTS					
Dimensions	TO-247AC 3L	www.vishay.com/doc?96138			
Differsions	TO-247AC 2L	www.vishay.com/doc?96144			
Part marking information	TO-247AC 3L	www.vishay.com/doc?95007			
Part marking information	TO-247AC 2L	www.vishay.com/doc?95442			
SPICE model		www.vishay.com/doc?96580			

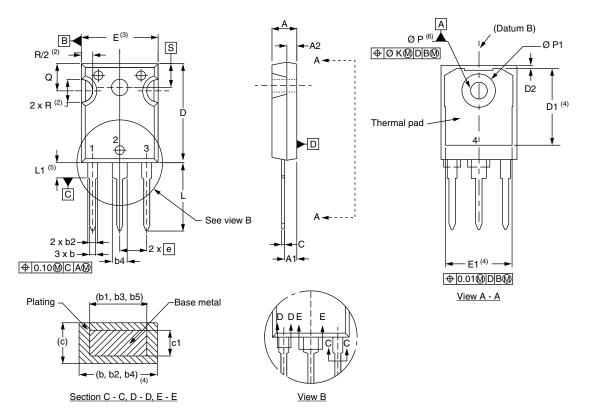
Revision: 28-Nov-2019 5 Document Number: 93571 For technical questions within your region: <u>DiodesAmericas@vishay.com</u>, <u>DiodesAsia@vishay.com</u>, <u>DiodesAsia@vishay.com</u>, <u>DiodesEurope@vishay.com</u>



Vishay Semiconductors

TO-247AC 3L

DIMENSIONS in millimeters and inches



SYMBOL	MILLIN	IETERS	INC	HES	NOTES
STMBOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.65	5.31	0.183	0.209	
A1	2.21	2.59	0.087	0.102	
A2	1.17	1.37	0.046	0.054	
b	0.99	1.40	0.039	0.055	
b1	0.99	1.35	0.039	0.053	
b2	1.65	2.39	0.065	0.094	
b3	1.65	2.34	0.065	0.092	
b4	2.59	3.43	0.102	0.135	
b5	2.59	3.38	0.102	0.133	
С	0.38	0.89	0.015	0.035	
c1	0.38	0.84	0.015	0.033	
D	19.71	20.70	0.776	0.815	3
D1	13.08	-	0.515	-	4

SYMBOL	MILLIMETERS		INC	NOTES	
STIVIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
D2	0.51	1.35	0.020	0.053	
E	15.29	15.87	0.602	0.625	3
E1	13.46	-	0.53	-	
е	5.46	BSC	0.215	BSC	
ØK	0.254		0.010		
L	14.20	16.10	0.559	0.634	
L1	3.71	4.29	0.146	0.169	
ØΡ	3.56	3.66	0.14	0.144	
Ø P1	-	7.39	-	0.291	
Q	5.31	5.69	0.209	0.224	
R	4.52	5.49	0.178	0.216	
S	5.51 BSC		0.217 BSC		
					•

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5M-1994
- (2) Contour of slot optional
- (3) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Thermal pad contour optional with dimensions D1 and E1
- (5) Lead finish uncontrolled in L1
- (6) Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- (7) Outline conforms to JEDEC® outline TO-247 with exception of dimension Q

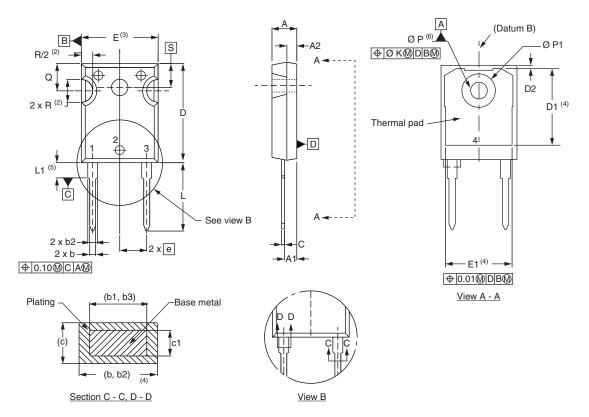
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Vishay Semiconductors

TO-247AC 2L

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES
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Α	4.65	5.31	0.183	0.209	
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